

WAFER PROCESSING APPARATUS

ABSTRACT

A wafer processing apparatus includes a chuck table for holding the wafer thereon, a grinding unit having a rotatable grinding wheel with an annular array of grindstones mounted thereon for grinding a surface of the wafer held on the chuck table, a cleaning unit for cleaning the wafer that has been ground by the grinding unit, and an etching unit for removing a strain from the ground surface of the wafer. The grinding wheel of the grinding unit is smaller in diameter than the wafer, enabling the grindstones mounted on the grinding wheel to thin down an inner region of the wafer that includes the ground surface, leaving an outer circumferential ring-shaped stiff portion on the wafer. The etching unit supplies an etching liquid to the inner region of the wafer inward of the outer circumferential ring-shaped stiff portion of the wafer for thereby removing a strain from the ground surface of the wafer.

[FIG. 2]